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AUSTIN AMERICAN TECHNOLOGY

The Science of Cleaning.

Free Technical Workshop!
PCB Cleaning: Challenges & Solutions

OVERVIEW

Over the past twenty years, the electronic manufacturing industry has seen cleaning (defluxing) become more necessary and more challenging. Never before has the removal of contamination from circuit assemblies been so important to a product's overall reliability. Increasing component and assembly densities, decreasing standoff heights, higher reflow temperatures, and increased reliability expectations have created a "perfect storm" that is driving manufacturers to seek cleaning solutions.

Join us in Rochester, New York for a free one day cleaning workshop. Four industry experts from Austin American Technology, Zestron, Kester, and Aqueous Technologies join forces to present valuable solutions to cleaning's most challenging issues.

This workshop will be presented free of charge at Rochester Institute of Technology, in Rochester, New York. Lunch will be provided.

Where:

Austin American Technology
Zestron
Kester &
Aqueous Technologies

Presents
PCB Cleaning:
Challenges & Solutions

Once commonplace, the cleaning of post-reflow circuit assemblies became increasingly eliminated due to the popularity of no-clean fluxes in the late 1980's and early 1990's.
Today, component and assembly miniturization, higher temperature reflow profiles, and increased reliability expectations have combined to reduce the volume of allowable contamination acceptable on an electronic assembly. The removal of flux and other process residues and cleanliness testing are among the fastest growing yet least understood processes in the electronic assembly industry today.
This one-day technical workshop will answer many common questions about cleaning and cleanliness testing. The workshop is free but seats are limited. A continental breakfast and lunch will be provided.

Register

Agenda

PCB Cleaning: Challenges & Solutions
Kester - Zestron - Aqueous Technologies - Austin American Technology

Time **Subject**

Rochester Institute of Technology
1 Lomb Memorial Drive
Rochester, NY 14623-5603

When:

Tuesday June 26, 2012
From 8:30 to 3:30 EDT

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For more information, please contact:

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8:45 **Welcome & Introductions**

9:00 **Peter Biocca, Kester**
"Reliability Challenges Caused by Solder Paste as well as Degreasing Pitch Width."

10:00 **Break**

10:30 **Ravi Parthasarathy, Zestron**
"Why clean PCBs?"
Industry trends & product reliability
Failure mechanisms
RMA, No-clean, OA
OA flux/paste - limitations of cleaning with DI H2O
How clean is clean - surface analytics

11:30 **Lunch & RIT Lab Tour**

1:00 **Michael Konrad, Aqueous Technologies**
"Defluxing Equipment Best Practices and Roadmap (Batch Focus)"
Machine configurations
Chemical management
Effluent management
SPC Data management
Operating cost analysis
SPC Data management
Cleanliness evaluation methods

2:00 **Steve Stach, Austin American Technology**
"Defluxing Equipment Best Practices (In-Line Focus)"
Optimizing the in-line process
Benefits of wash bath chemistry dosing system
Impact of evaporitve loss and techniques to minimize
Effluent streams associated with chemistry cleaning process
How to manage cost effectively

3:00 **Panel Discussion**

3:30 **Adjourn**

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